

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: **Ghoshal et al.**

Serial No.: **Not Assigned**

Filed: **February 11, 2002**

For: **Enhanced Interface  
Thermoelectric Coolers with All Metal  
Tips**

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Group Art Unit: **1741**

Examiner: **Parsons, Thomas H.**

Attorney Docket No.: **AUS920000414US2**

**Certificate of Mailing Under 37 C.F.R. § 1.8(a)**

I hereby certify this correspondence is being deposited with the United States Postal Service as First Class mail in an envelope addressed to: Assistant Commissioner of Patents, Washington, D.C. 20231 on February 11, 2002.

By.

Krista Douthitt

**PRELIMINARY AMENDMENT**

Assistant Commissioner of Patents  
Washington, D.C. 20231

Sir:

No fees are believed to be necessary. If, however, any fees are required, I authorize the Commissioner to charge these fees to Deposit Account No. 09-0447. No extension of time is believed to be necessary. If, however, an extension of time is necessary, I authorize the Commissioner to charge the necessary extension fees to Deposit Account No. 09-0447.

Prior to examination of this application, please amend the above-identified application as follows:

**IN THE SPECIFICATION:**

On page one, before the BACKGROUND OF THE INVENTION, please insert the following paragraph:

This application is a divisional of application number 09/731,616,  
filed December 7, 2000, status allowed.

Please delete the paragraph beginning on page 1, line 9, and replace with the following:

The present application is related to co-pending U.S. Patent Application Serial No. 09/731,997 (IBM Docket No. **AUS9-2000-0415-US1**) entitled "THERMOELECTRIC COOLERS WITH ENHANCED STRUCTURED INTERFACES" filed on December 7, 2000, to co-pending U.S. Patent Application Serial No. 09/731,999 (IBM Docket No. **AUS9-2000-0564-**

US1) entitled "COLD POINT DESIGN FOR EFFICIENT THERMOELECTRIC COOLERS" filed on December 7, 2000, and to co-pending U.S. Patent Application Serial No. 09/731,614 (IBM Docket No. AUS9-2000-0556-US1) entitled "ENHANCED INTERFACE THERMOELECTRIC COOLERS USING ETCHED THERMOELECTRIC MATERIAL TIPS" filed on December 7, 2000. The content of the above mentioned commonly assigned, co-pending U. S. Patent applications are hereby incorporated herein by reference for all purposes.

**IN THE CLAIMS:**

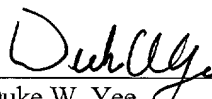
Please cancel claims 1-8.

**REMARKS**

Claims 1-8 have been canceled. Claims 9-27 remain in the application. These claims are believed to be in condition for allowance. The examiner is invited to call the undersigned at the below-listed telephone number if in the opinion of the examiner such a telephone conference would expedite or aid the prosecution and examination of this application.

Date: February 11, 2002

Respectfully submitted,

  
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## **APPENDIX: REDACTED PARAGRAPH**

The redacted paragraph that began on page 1, at line 9 is as follows:

The present application is related to co-pending U.S. Patent Application Serial No. 09/731,997 [ ] (IBM Docket No. **AUS9-2000-0415-US1**) entitled "THERMOELECTRIC COOLERS WITH ENHANCED STRUCTURED INTERFACES" filed on December 7, 2000 [ ], to co-pending U.S. Patent Application S[erial No. 09/731,999 [ ] (IBM Docket No. **AUS9-2000-0564-US1**) entitled "COLD POINT DESIGN FOR EFFICIENT THERMOELECTRIC COOLERS" filed on December 7, 2000 [ ], and to co-pending U.S. Patent Application S[erial No. 09/731,614 [ ] (IBM Docket No. **AUS9-2000-0556-US1**) entitled "ENHANCED INTERFACE THERMOELECTRIC COOLERS USING ETCHED THERMOELECTRIC MATERIAL TIPS" filed on December 7, 2000 [ ]. The content of the above mentioned commonly assigned, co-pending U. S. Patent applications are hereby incorporated herein by reference for all purposes.